19-2813; Rev 1; 11/03

3V/5V, 6dB Video Buffer with Sync-Tip Clamp and 150nA Shutdown Current

General Description

The MAX4090 3V/5V, 6dB video buffer with sync-tip clamp, and low-power shutdown mode is available in tiny SOT23 and SC70 packages. The MAX4090 is designed to drive DC-coupled, 150Ω back-terminated video loads in portable video applications such as digital still cams, portable DVD players, digital camcorders, PDAs, video-enabled cell phones, portable game systems, and notebook computers. The input clamp positions the video waveform at the output and allows the MAX4090 to be used as a DC-coupled output driver.

The MAX4090 operates from a single 2.7V to 5.5V supply and consumes only 6.5mA of supply current. The low-power shutdown mode reduces the supply current to 150nA, making the MAX4090 ideal for low-voltage, battery-powered video applications.

The MAX4090 is available in tiny 6-pin SOT23 and SC70 packages and is specified over the extended -40°C to +85°C temperature range.

Features

- ♦ Single-Supply Operation from 2.7V to 5.5V
- ♦ Input Sync-Tip Clamp
- ♦ DC-Coupled Output
- ♦ Low-Power Shutdown Mode Reduces Supply Current to 150nA
- ♦ Available in Space-Saving SOT23 and SC70 Packages

Applications

Portable Video/Game Systems/DVD Players

Digital Camcorders/Televisions/Still Cameras

PDAs

Video-Enabled Cell Phones

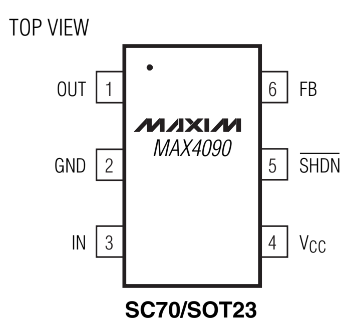
Notebook Computers

Portable/Flat-Panel Displays

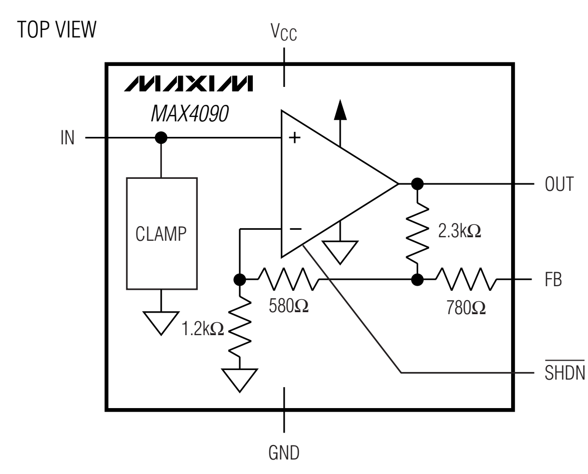
Ordering Information

PART	TEMP RANGE	PIN-PACKAGE	TOP MARK
MAX4090EXT-T	-40°C to +85°C	6 SC70-6	ABM
MAX4090EUT-T	-40°C to +85°C	6 SOT23-6	ABOX

Pin Configuration



Block Diagram



ABSOLUTE MAXIMUM RATINGS

V_{CC} to GND .... -0.3V to +6V
OUT, FB, $\overline{SHDN}$ to GND .... -0.3V to (V_{CC} + 0.3V)
IN to GND (Note 1) .... V_{CLP} to (V_{CC} + 0.3V)
IN Short-Circuit Duration from -0.3V to V_{CLP} 1min
Output Short-Circuit Duration to V_{CC} or GND .... Continuous
Continuous Power Dissipation (T_A = +70°C)
6-Pin SOT23 (derate 8.7mW/°C above +70°C) 695mW
6-Pin SC70 (derate 3.1mW/°C above +70°C) 245mW
Operating Temperature Range .... -40°C to +85°C
Junction Temperature .... +150°C
Storage Temperature Range .... -65°C to +150°C
Lead Temperature (soldering, 10s) .... +300°C

Note 1: V_{CLP} is the input clamp voltage as defined in the *DC Electrical Characteristics* table.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

(V_{CC} = 3.0V, GND = 0V, C_{IN} = 0.1µF from IN to GND, R_L = infinity to GND, FB shorted to OUT, $\overline{SHDN}$ = 3.0V, T_A = -40°C to +85°C. Typical values are at T_A = +25°C, unless otherwise noted.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Supply Voltage Range	V_{CC}	Guaranteed by PSRR		2.7		5.5	V
Quiescent Supply Current	I_{CC}	V_{IN} = V_{CLP}	V_{CC} = 3V		6.5	10	mA
			V_{CC} = 5V		6.5	10	
Shutdown Supply Current	$I_{\overline{SHDN}}$	$\overline{SHDN}$ = 0V			0.15	1	µA
Input Clamp Voltage	V_{CLP}	Input referred		0.27	0.38	0.47	V
Input Voltage Range	V_{IN}	Inferred from voltage gain (Note 3)		V_{CLP}		1.45	V
Input Bias Current	I_{BIAS}	V_{IN} = 1.45V			22.5	35	µA
Input Resistance		V_{CLP} + 0.5V < V_{IN} < V_{CLP} + 1V			3		MΩ
Voltage Gain	A_V	R_L = 150Ω, 0.5V < V_{IN} < 1.45V (Note 4)		1.9	2	2.1	V/V
Power-Supply Rejection Ratio	PSRR	2.7V < V_{CC} < 5.5V		60	80		dB
Output Voltage High Swing	V_{OH}	R_L = 150Ω to GND	V_{CC} = 3V	2.55	2.7		V
			V_{CC} = 5V	4.3	4.6		
Output Voltage Low Swing	V_{OL}	R_L = 150Ω to GND			V_{CLP}	0.47	V
Output Current	I_{OUT}	Sourcing, R_L = 20Ω to GND		45	85		mA
		Sinking, R_L = 20Ω to V_{CC}		40	85		
Output Short-Circuit Current	I_{SC}	OUT shorted to V_{CC} or GND			110		mA
$\overline{SHDN}$ Logic-Low Threshold	V_{IL}					V_{CC} x 0.3	V
$\overline{SHDN}$ Logic-High Threshold	V_{IH}			V_{CC} x 0.7			V
$\overline{SHDN}$ Input Current	I_{IH}				0.003	1	µA
Shutdown Output Impedance	R_{OUT} (Disabled)	$\overline{SHDN}$ = 0V	At DC		4		kΩ
			At 3.58MHz or 4.43MHz		2		

AC ELECTRICAL CHARACTERISTICS

(V_{CC} = 3.0V, GND = 0V, FB shorted to OUT, C_{IN} = 0.1µF, R_{IN} = 75Ω to GND, R_L = 150Ω to GND, $\overline{SHDN}$ = V_{CC}, T_A = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Small-Signal -3dB Bandwidth	BW_{SS}	V_{OUT} = 100mV_{P-P}			55		MHz
Large-Signal -3dB Bandwidth	BW_{LS}	V_{OUT} = 2V_{P-P}			45		MHz
Small-Signal 0.1dB Gain Flatness	$BW_{0.1dBSS}$	V_{OUT} = 100mV_{P-P}			25		MHz
Large-Signal 0.1dB Gain Flatness	$BW_{0.1dBLS}$	V_{OUT} = 2V_{P-P}			17		MHz
Slew Rate	SR	V_{OUT} = 2V step			275		V/µs
Settling Time to 0.1%	t_S	V_{OUT} = 2V step			25		ns
Power-Supply Rejection Ratio	PSRR	f = 100kHz			50		dB
Output Impedance	Z_{OUT}	f = 5MHz			2.5		Ω
Differential Gain	DG	NTSC	V_{CC} = 3V		1		%
			V_{CC} = 5V		0.5		
Differential Phase	DP	NTSC	V_{CC} = 3V		0.8		Degrees
			V_{CC} = 5V		0.5		
Group Delay	D/dT	f = 3.58MHz or 4.43MHz			20		ns
Peak Signal to RMS Noise	SNR	V_{IN} = 1V_{P-P}, 10MHz BW			65		dB
Droop		C_{IN} = 0.1µF (Note 4)			2	3	%
$\overline{SHDN}$ Enable Time	t_{ON}	V_{IN} = V_{CLP} + 1V, $\overline{SHDN}$ = 3V, V_{OUT} settled to within 1% of the final voltage			250		ns
$\overline{SHDN}$ Disable Time	t_{OFF}	V_{IN} = V_{CLP} + 1V, $\overline{SHDN}$ = 0V, V_{OUT} settled to below 1% of the output voltage			50		ns

Note 2: All devices are 100% production tested at T_A = +25°C. Specifications over temperature limits are guaranteed by design.

Note 3: Voltage gain (A_V) is referenced to the clamp voltage, i.e., an input voltage of V_{IN} = V_{CLP} + VI would produce an output voltage of V_{OUT} = V_{CLP} + A_V x VI.

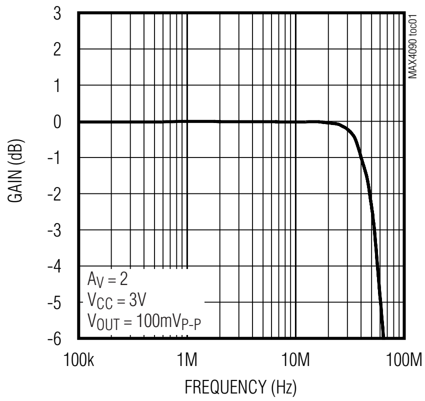
Note 4: Droop is guaranteed by the Input Bias Current specification.

3V/5V, 6dB Video Buffer with Sync-Tip Clamp and 150nA Shutdown Current

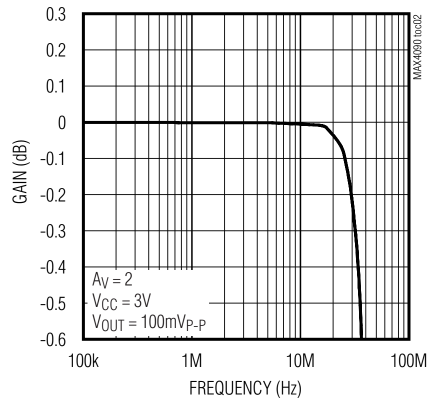
Typical Operating Characteristics

(V_{CC} = 3.0V, GND = 0V, FB shorted to OUT, C_{IN} = 0.1µF, R_{IN} = 75Ω to GND, R_L = 150Ω to GND, $\overline{SHDN}$ = V_{CC}, T_A = +25°C, unless otherwise noted.)

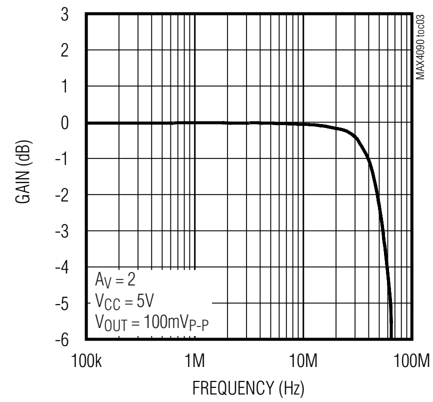
SMALL-SIGNAL GAIN vs. FREQUENCY



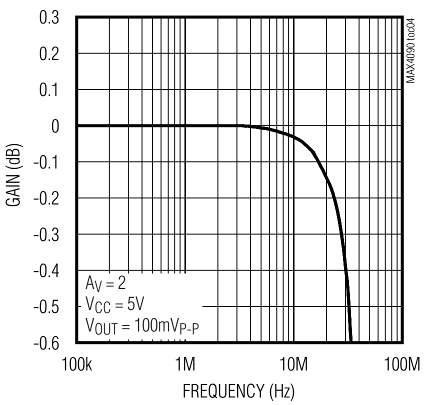
SMALL-SIGNAL GAIN FLATNESS vs. FREQUENCY



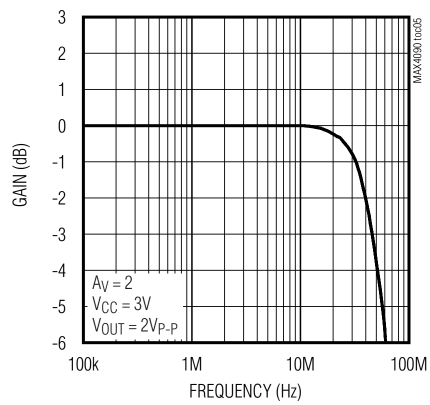
SMALL-SIGNAL GAIN vs. FREQUENCY



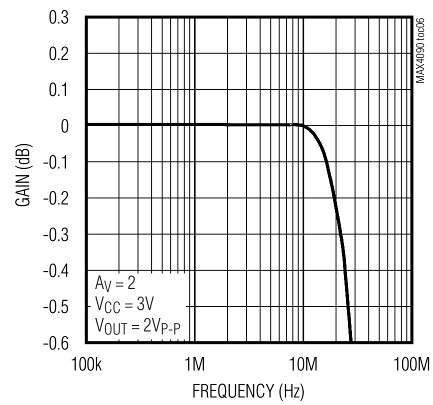
SMALL-SIGNAL GAIN FLATNESS vs. FREQUENCY



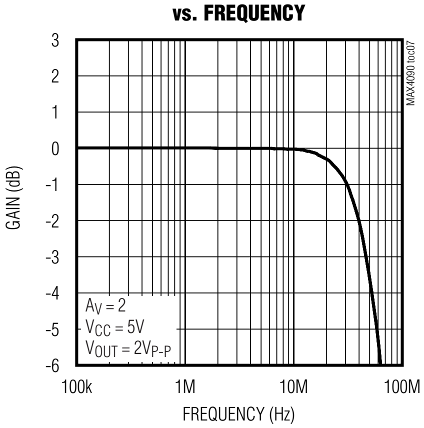
LARGE-SIGNAL GAIN vs. FREQUENCY



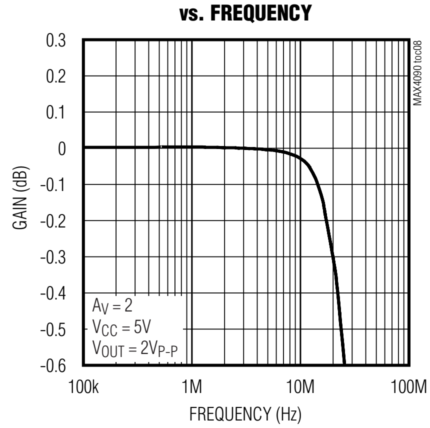
LARGE-SIGNAL GAIN FLATNESS vs. FREQUENCY



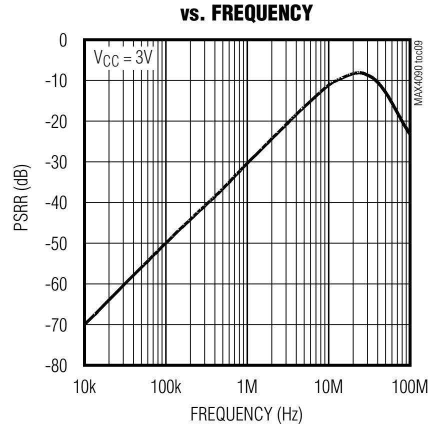
LARGE-SIGNAL GAIN vs. FREQUENCY



LARGE-SIGNAL GAIN FLATNESS vs. FREQUENCY



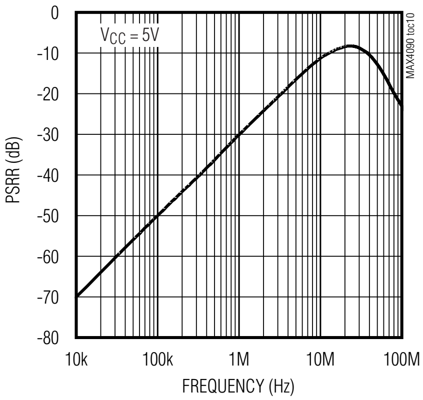
POWER-SUPPLY REJECTION RATIO vs. FREQUENCY



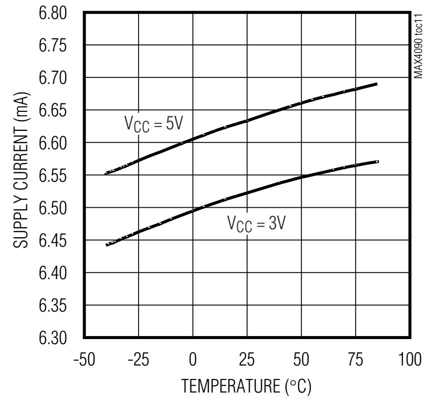
Typical Operating Characteristics (continued)

(V_{CC} = 3.0V, GND = 0V, FB shorted to OUT, C_{IN} = 0.1µF, R_{IN} = 75Ω to GND, R_L = 150Ω to GND, $\overline{SHDN}$ = V_{CC}, T_A = +25°C, unless otherwise noted.)

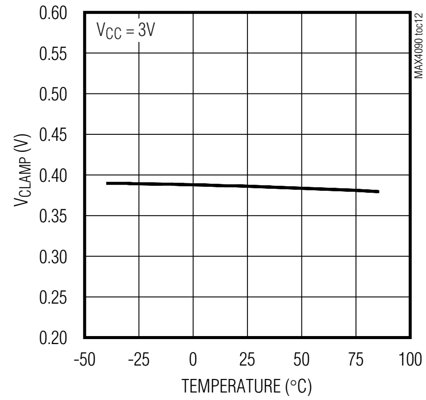
POWER-SUPPLY REJECTION RATIO vs. FREQUENCY



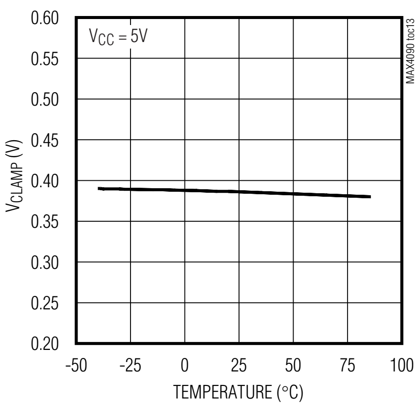
QUIESCENT SUPPLY CURRENT vs. TEMPERATURE



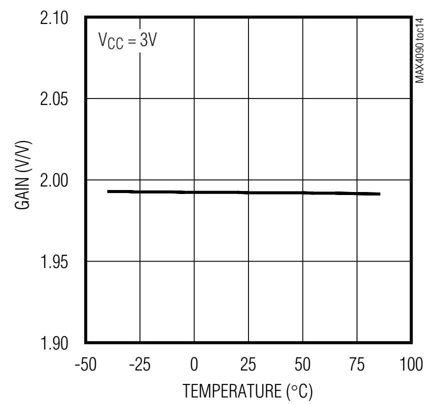
CLAMP VOLTAGE vs. TEMPERATURE



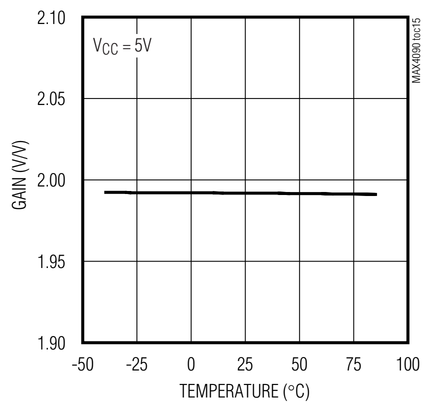
CLAMP VOLTAGE vs. TEMPERATURE



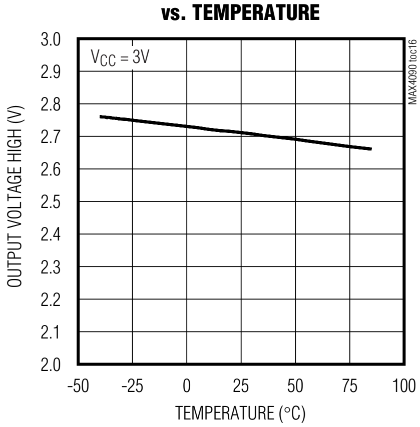
VOLTAGE GAIN vs. TEMPERATURE



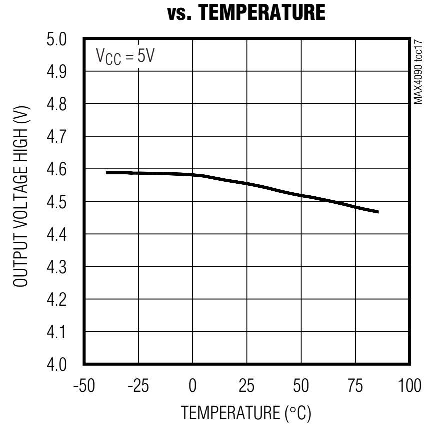
VOLTAGE GAIN vs. TEMPERATURE



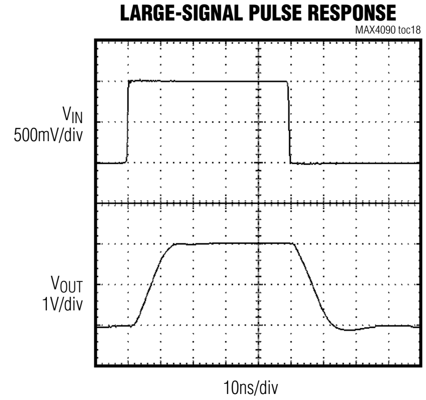
OUTPUT VOLTAGE HIGH SWING vs. TEMPERATURE



OUTPUT VOLTAGE HIGH SWING vs. TEMPERATURE



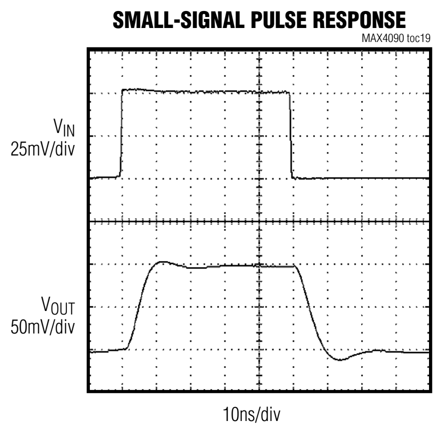
LARGE-SIGNAL PULSE RESPONSE

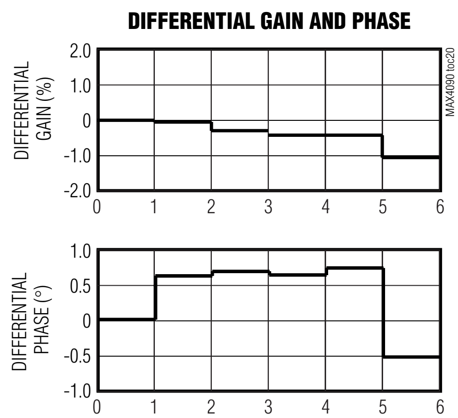


3V/5V, 6dB Video Buffer with Sync-Tip Clamp and 150nA Shutdown Current

Typical Operating Characteristics (continued)

(V_{CC} = 3.0V, GND = 0V, FB shorted to OUT, C_{IN} = 0.1µF, R_{IN} = 75Ω to GND, R_L = 150Ω to GND, $\overline{SHDN}$ = V_{CC}, T_A = +25°C, unless otherwise noted.)

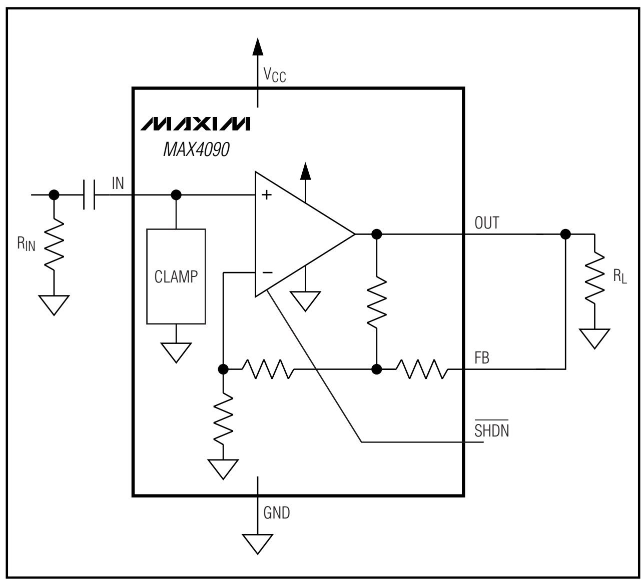




Pin Description

PIN	NAME	FUNCTION
1	OUT	Video Output
2	GND	Ground
3	IN	Video Input
4	V_{CC}	Power-Supply Voltage. Bypass with a 0.1µF capacitor to ground as close to pin as possible.
5	$\overline{SHDN}$	Shutdown. Pull $\overline{SHDN}$ low to place the MAX4090 in low-power shutdown mode.
6	FB	Feedback. Short to V_{CC}.

Typical Application Circuit



Detailed Description

The MAX4090 3V/5V, 6dB video buffer with sync-tip clamp and low-power shutdown mode is available in tiny SOT23 and SC70 packages. The MAX4090 is designed to drive DC-coupled, 150Ω back-terminated video loads in portable video applications such as digital still cams, portable DVD players, digital camcorders, PDAs, video-enabled cell phones, portable game systems, and notebook computers. The input clamp positions the video waveform at the output and allows the MAX4090 to be used as a DC-coupled output driver.

The MAX4090 operates from a single 2.7V to 5.5V supply and consumes only 6.5mA of supply current. The low-power shutdown mode reduces the supply current to 150nA, making the MAX4090 ideal for low-voltage, battery-powered video applications.

The input signal to the MAX4090 is AC-coupled through a capacitor into an active sync-tip clamp circuit, which places the minimum of the video signal at approximately 0.38V. The output buffer amplifies the video signal while still maintaining the 0.38V clamp voltage at the output. For example, if V_{IN} = 0.38V, then V_{OUT} = 0.38V. If V_{IN} = (0.38V + 1V) = 1.38V, then V_{OUT} = (0.38V + 2 X (1V)) = 2.38V. The net result is that a 2V video output signal swings within the usable output voltage range of the output buffer when V_{CC} = 3V.

Shutdown Mode

The MAX4090 features a low-power shutdown mode ($I_{\overline{SHDN}}$ = 150nA) for battery-powered/portable applications. Pulling the $\overline{\text{SHDN}}$ pin high enables the output. Connecting the $\overline{\text{SHDN}}$ pin to ground (GND) disables the output and places the MAX4090 into a low-power shutdown mode.

Applications Information

Input Coupling the MAX4090

The MAX4090 input must be AC-coupled because the input capacitor stores the clamp voltage. The MAX4090 requires a typical value of 0.1µF for the input clamp to meet the Line Droop specification. A minimum of a ceramic capacitor with an X7R temperature coefficient is recommended to avoid temperature-related problems with Line Droop. For extended temperature operation, such as outdoor applications, or where the impressed voltage is close to the rated voltage of the capacitor, a film dielectric is recommended. Increasing the capacitor value slows the clamp capture time. Values above 0.5µF should be avoided since they do not improve the clamp's performance.

The active sync-tip clamp also requires that the input impedance seen by the input capacitor be less than 100Ω typically to function properly. This is easily met by the 75Ω input resistor prior to the input-coupling capacitor and the back termination from a prior stage. Insufficient input resistance to ground causes the MAX4090 to appear to oscillate. Never operate the MAX4090 in this mode.

Layout and Power-Supply Bypassing

The MAX4090 operates from single 2.7V to 5.5V supply. Bypass the supply with a 0.1µF capacitor as close to the pin as possible. Maxim recommends using microstrip and stripline techniques to obtain full bandwidth. To ensure that the PC board does not degrade the device's performance, design it for a frequency greater than 1GHz. Pay careful attention to inputs and outputs to avoid large parasitic capacitance. Whether or not you use a constant-impedance board, observe the following design guidelines:

- Do not use wire-wrap boards; they are too inductive.
- Do not use IC sockets; they increase parasitic capacitance and inductance.
- Use surface-mount instead of through-hole components for better, high-frequency performance.
- Use a PC board with at least two layers; it should be as free from voids as possible.
- Keep signal lines as short and as straight as possible. Do not make 90° turns; round all corners.

Chip Information

TRANSISTOR COUNT: 755

PROCESS: BiCMOS

3V/5V, 6dB Video Buffer with Sync-Tip Clamp and 150nA Shutdown Current

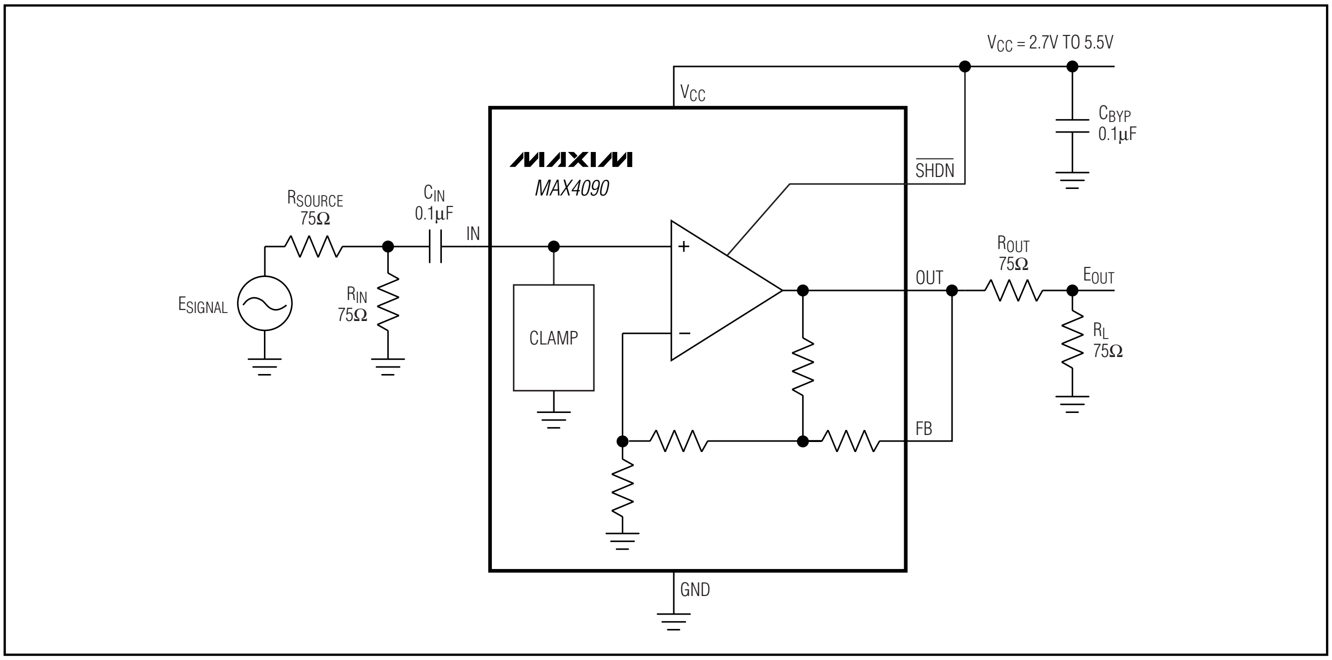
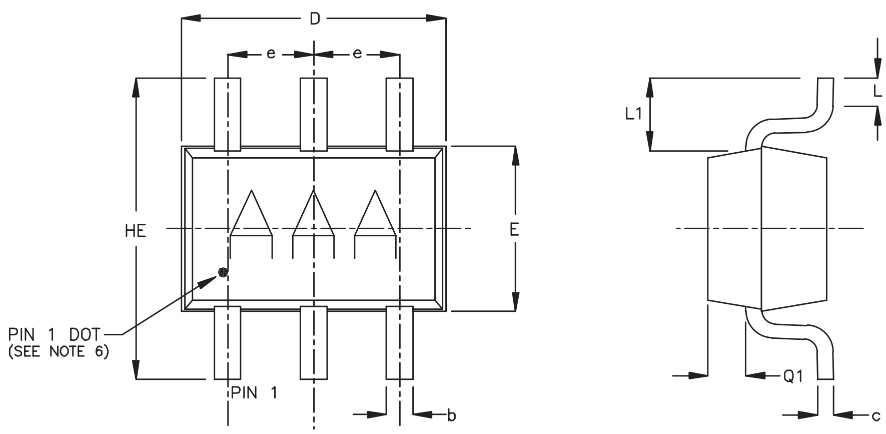


Figure 1. Typical Operating Circuit

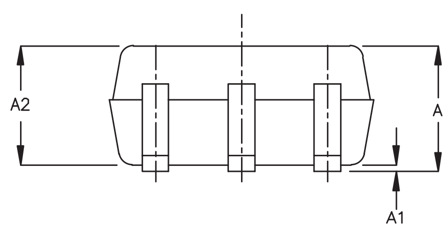
Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to **www.maxim-ic.com/packages**.)

SC70, 6L.EPS



SYMBOL	MIN	MAX
e	0.65 BSC	
D	1.80	2.20
b	0.15	0.30
E	1.15	1.35
HE	1.80	2.40
Q1	0.10	0.40
A2	0.80	1.00
A1	0.00	0.10
A	0.80	1.10
c	0.10	0.18
L	0.10	0.30
L1	0.425 TYP.	



1. ALL DIMENSIONS ARE IN MILLIMETERS
2. DIMENSIONS ARE INCLUSIVE OF PLATING
3. DIMENSIONS ARE EXCLUSIVE OF MOLD FLASH & METAL BURR
4. ALL SPECIFICATIONS COMPLY TO EIAJ SC70
5. COPLANARITY 4 MILS. MAX.
6. PIN 1 I.D. DOT

MAXIM
PROPRIETARY INFORMATION
TITLE:
PACKAGE OUTLINE, SC70, 6L

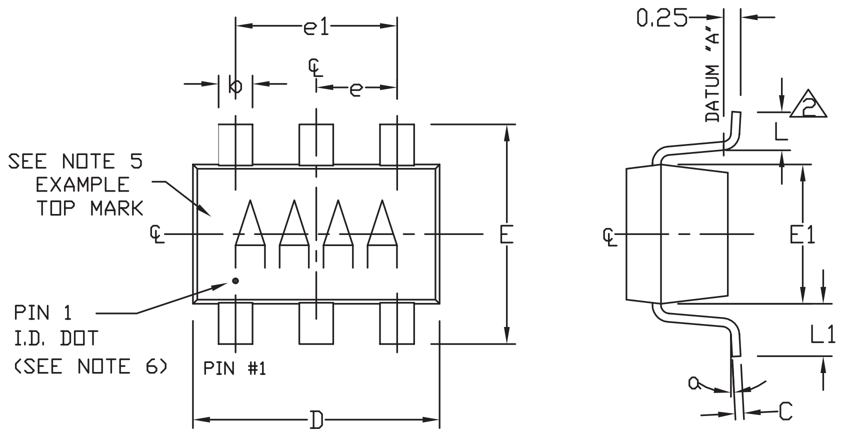
APPROVAL	DOCUMENT CONTROL NO.	REV	
	21-0077	B	1/1

3V/5V, 6dB Video Buffer with Sync-Tip Clamp and 150nA Shutdown Current

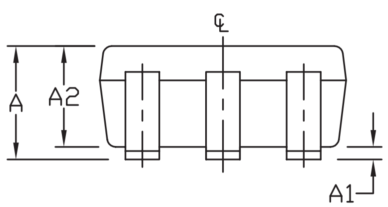
Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to **www.maxim-ic.com/packages**.)

6LSOT.EPS



SYMBOL	MIN	MAX
A	0.90	1.45
A1	0.00	0.15
A2	0.90	1.30
b	0.35	0.50
C	0.08	0.20
D	2.80	3.00
E	2.60	3.00
E1	1.50	1.75
L	0.35	0.60
L1	0.60 REF.	
e1	1.90 BSC.	
e	0.95 BSC.	
α	0°	10°



NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. FOOT LENGTH MEASURED AT INTERCEPT POINT BETWEEN DATUM A & LEAD SURFACE.
3. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASH & METAL BURR. MOLD FLASH, PROTRUSION OR METAL BURR SHOULD NOT EXCEED 0.25 MM.
4. PACKAGE OUTLINE INCLUSIVE OF SOLDER PLATING.
5. PIN 1 IS LOWER LEFT PIN WHEN READING TOP MARK FROM LEFT TO RIGHT. (SEE EXAMPLE TOP MARK)
6. PIN 1 I.D. DOT IS 0.3 MM ø MIN. LOCATED ABOVE PIN 1.
7. MEETS JEDEC MO178, VARIATION AB.
8. SOLDER THICKNESS MEASURED AT FLAT SECTION OF LEAD BETWEEN 0.08mm AND 0.15mm FROM LEADTIP.
9. LEAD TO BE COPLANAR WITHIN 0.1 MM.

DALLAS SEMICONDUCTOR MAXIM
PROPRIETARY INFORMATION
TITLE: PACKAGE OUTLINE, SOT-23, 6L

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0058	F	1/1